

In2p3





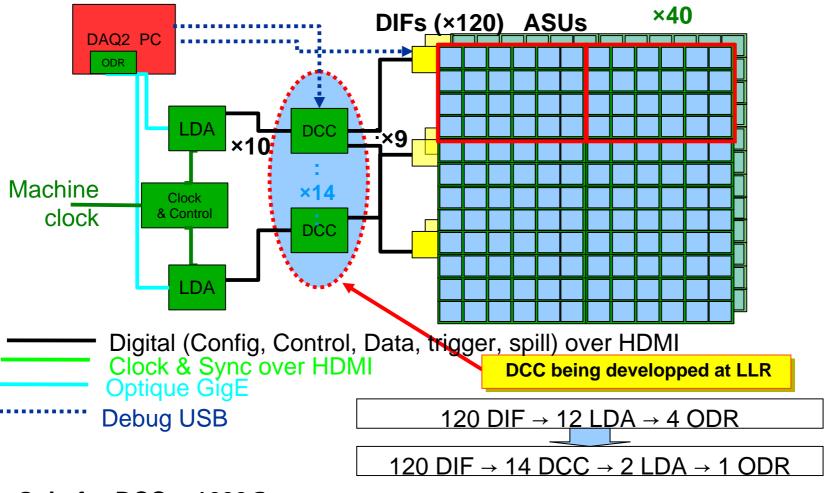
## Status of the DCC and DAQ Test Bench at LLR

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#### **DAQ** overview



Gain for DCC ≤ 1600€

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## Everything is resumed here

• Main specification :

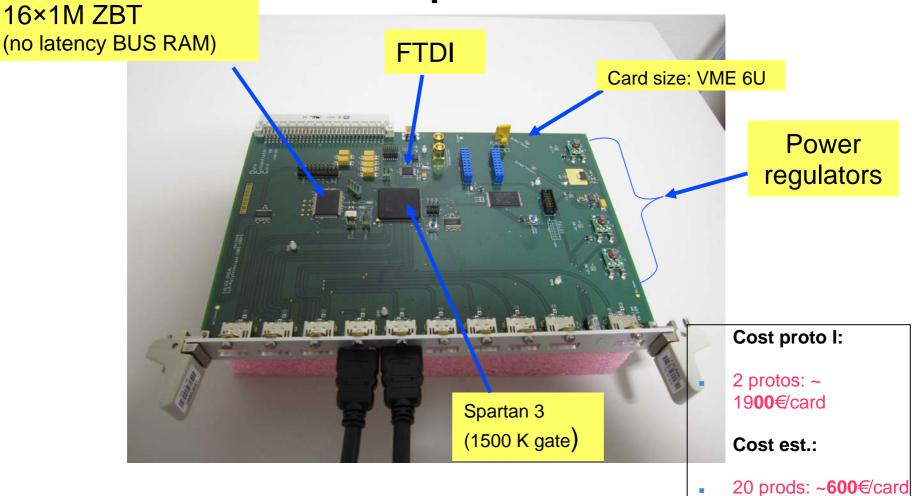
Reduce the number of LDA and ODR for the DHCAL & optimize the data flux

- Without DCC :
  - 3 Difs/layer (40 Layers)
  - 10 Difs/LDA => 12 LDA and 3 ODR
- With DCC, we need :
- 9 DIFs/DCC => 14 DCC => 2 LDA and 1 ODR
- Characteristics :
  - To be transparent between DIF and LDA
  - Broadcast all fast commands from LDA to all DIFs
  - Send the packet R/O one after the other
  - Read 9 DIFs (objective)
  - Availability of USB access
- Firmware : Re-use as far as possible existing VHDL blocks (Marc)
- Homemade card
  - Cheaper: objective (max 600 €/card) for the production



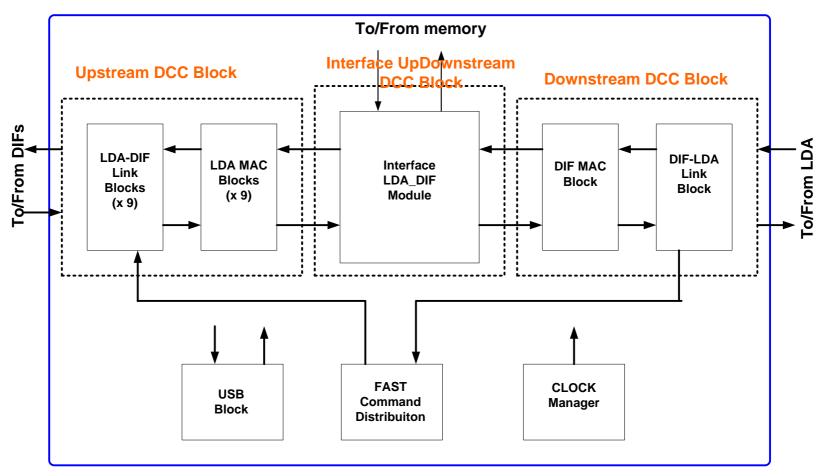


## **DCC** picture





## FPGA architecture by functionalities



#### **TOP DCC**

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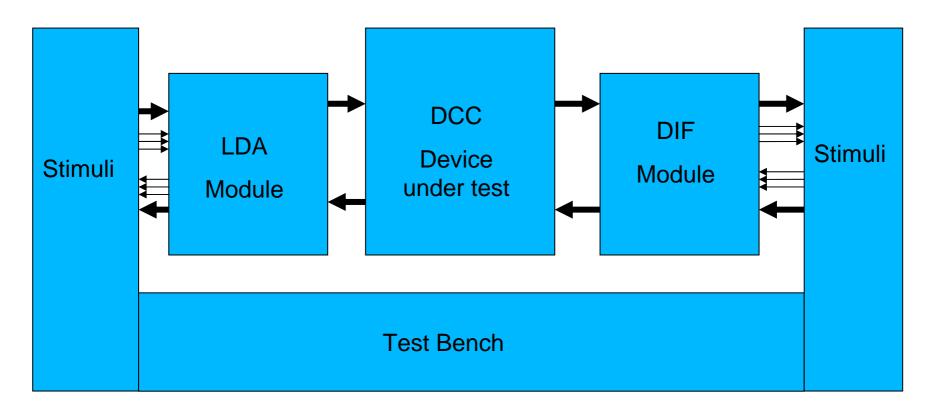
### **VHDL Blocks**

- •All VHDL blocks are designed
- •Some bugs are still present but all are identified
  - End Oct. : Bug resolved
  - End Nov. : Validation of VHDL in test bench
  - End Dec. : Full validation of DCC





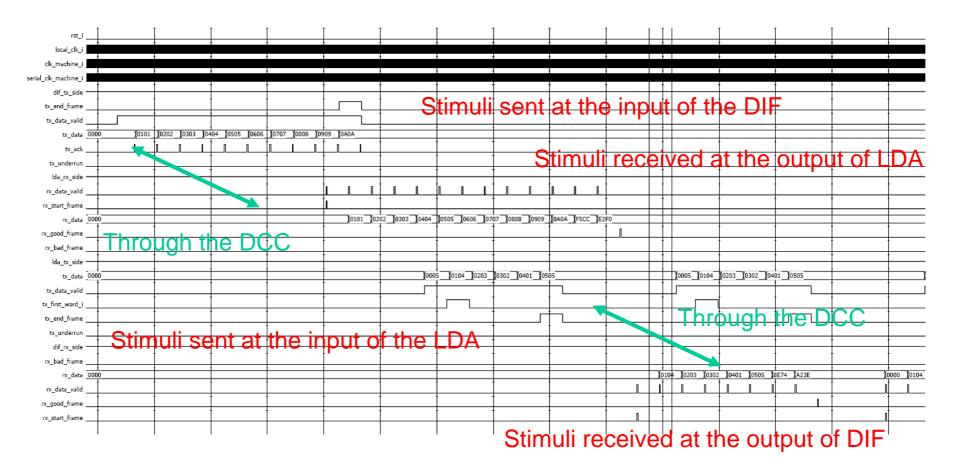
#### **VHDL** Test Bench







#### Example of simulation

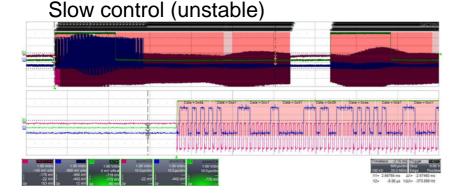


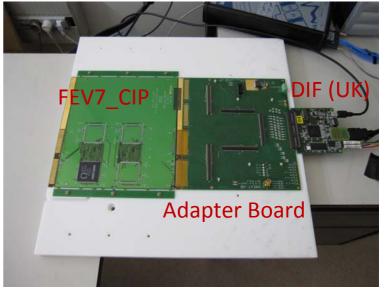


# ECAL : First SLAB prototype assembled (03/07/09)

- Basic firmware for the DIF is developed
- 50 MHz
- HDMI/USB multiplexed
- Unique interface inside DIF
- Hardware test have started by the end

```
of August
FCMD
BTCMD
```





- Connexion to SPIROC2 should be effective within 2 weeks
- More details in ECAL session

CALICE week, Lyon, 17/09/09, Rémi Cornat

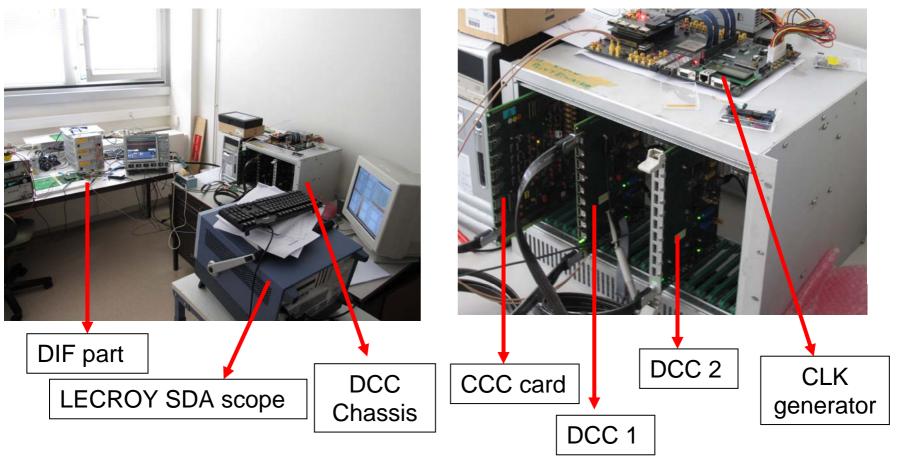




#### Test bench at LLR

#### Test Bench overview

#### CCC & DCC Chassis

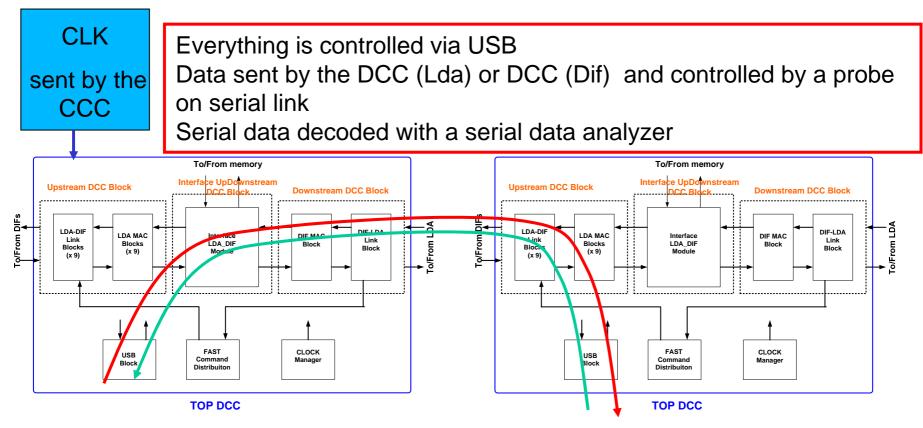


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## Test with two DCC

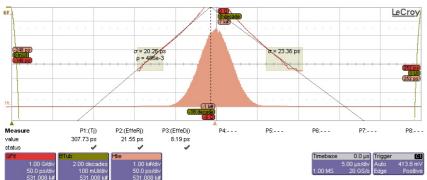


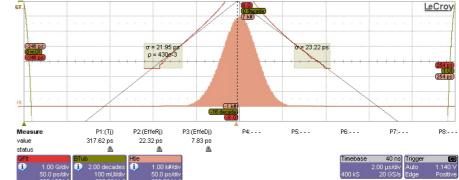
Link DCC(LDA) to DCC(DIF) via USB Link DCC(DIF) to DCC(LDA) via USB





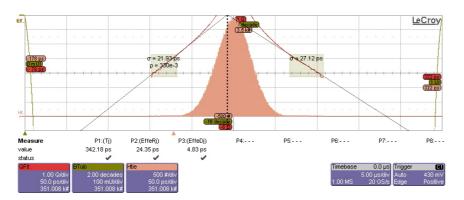
#### First test (clock) ccc => dcc => dif

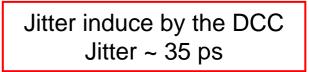




Jitter at the input of DCC : Tj = 317 ps

Jitter at the input of CCC : Tj = 307 ps





Jitter at the input of DIF : Tj = 342 ps

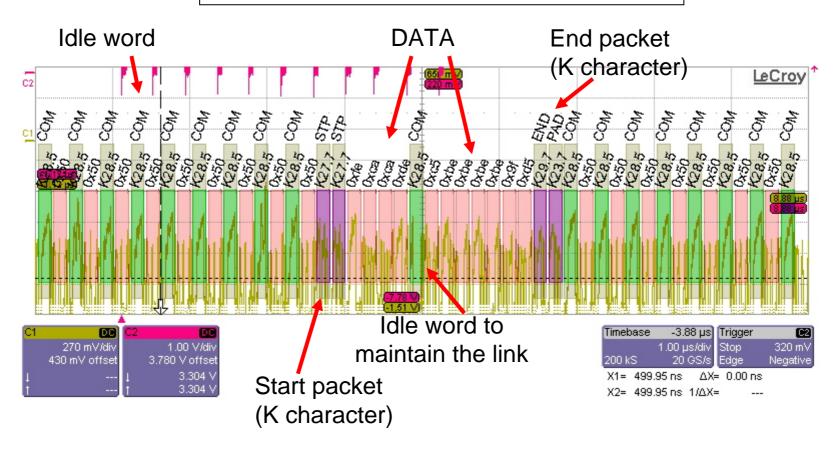
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#### Some results on serial link

Data sent from DCC(DIF) to DCC(LDA)





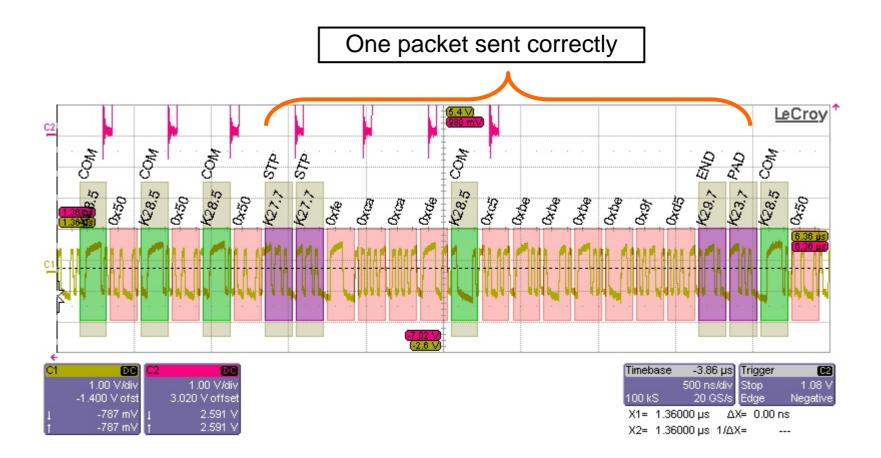
## Data sent from DCC(DIF) to DCC(LDA)

2 packets data sent



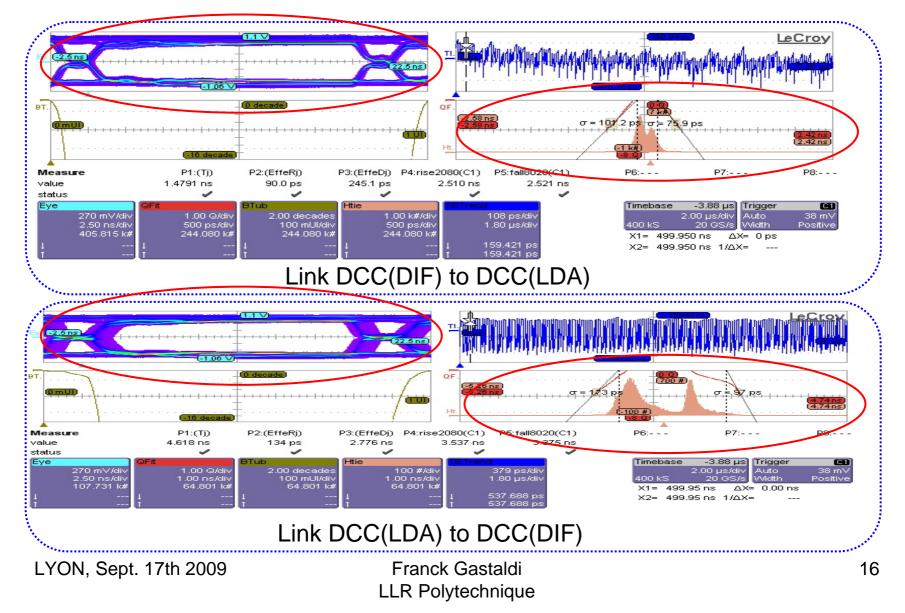


# Data sent from DCC(LDA) to DCC(DIF)





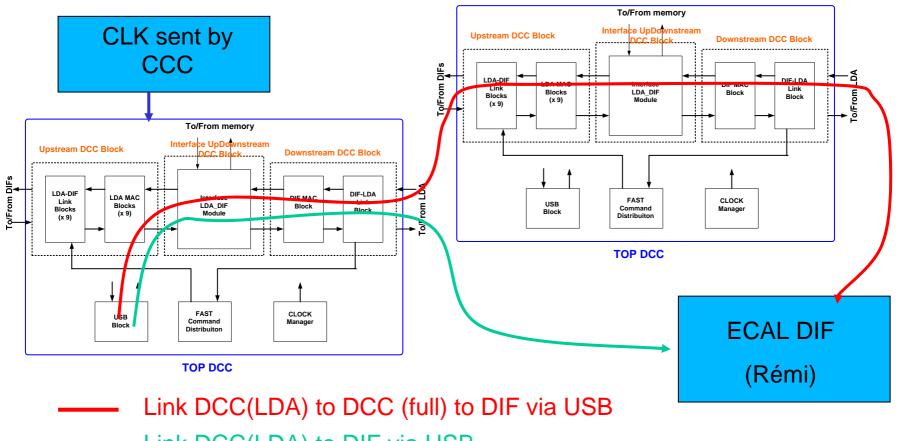








## Test with two DCC and one DIF



Link DCC(LDA) to DIF via USB





## Results

Link	Fast Command	Block Transfer	Data
DCC (Ida) →DIF	$\checkmark$	$\checkmark$	
DCC (Ida) $\rightarrow$ DCC (full) $\rightarrow$ DIF	$\checkmark$	$\checkmark$	
DIF → DCC (Lda)			To do
$DIF \rightarrow DCC \text{ (full)} \rightarrow DCC \text{ (Lda)}$			To do
$DIF \rightarrow DCC \rightarrow LDA$	To do	To do	To do
$LDA \rightarrow DCC \rightarrow DIF$	To do	To do	To do

✓ : Validate

#### $\checkmark$ : do not work for the moment





### Conclusion

- Firmware is running on the DCC
- Until end of year:
  - Tests & validation of VHDL code implemented on the DCC
  - Test of Multi-channel on the DCC
  - Test of a real DAQ Chain (ODR,LDA,DCC,DIF)
  - Improvement of DCC card (layout) before production
- DCC Production (early of next year)
  - February 2010 : PCB production
  - March 2010 : PCB cabling
  - April June 2010: tests at LLR
- Full DAQ : summer 2010





## Remarks for the thinking

- Where the LDA will be installed in test beam?
- What is the optimal length between the DIF and the DCC or LDA chassis ?

 $(\rightarrow$  the length of HDMI cable)

- Should we use a special HDMI cable ?
- Who is responsible for power distribution ?
   Should we go with our power supply ?
- Should we think of EMC and grounding problem ?

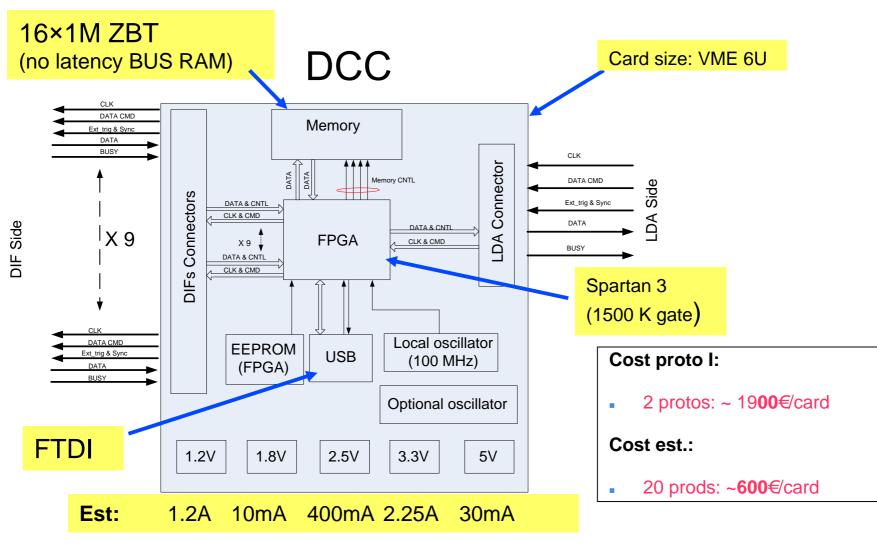
## Back up

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#### Card overview



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